



Uniform and reproducible fine line Developing

To achieve well defined edge shapes even for ultra fine lines we use specific fluid dynamics and oscillation

Areas of application

- Developing of dry film and liquid photo resists
- Developing of solder masks
- For carbonate and all commercial developers
- For flexible material or reel to reel

Features and benefits

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| <ul style="list-style-type: none"> • Optimised fluid dynamics with high flow rates • Fan nozzles with slim spray angles • Staggered spray nozzle configuration • Nozzles aligned to spray in conveyor gap • Oscillation perpendicular to working direction • Enhanced pumps for solder mask developing • Optional: closed loop process control | <ul style="list-style-type: none"> • Uniform line developing • Inline quick release mesh filters with safety switch • Integrated post developer for enhanced uniformity • Compact cascade rinsing • Suitable for developing 15/15 µm structures • Uniformity 5 - 10% • > 600 developing machines installed worldwide |
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PCM structure



Technical Data Höllmüller EVOLUTION - Developing

Process	• Resist Developing of different resists and solder masks					
	• Rinsing					
	• Drying					
	• Dwell time	45 sec liquid resist				
		60 sec dry film				
		90 sec solder mask				
• Process Temperature		25 - 35°C (77 - 95 °F)				
Dimensions	• Typical PCB applications					
	• Transport Speed	0.5 (1.65)	1.0 (3.3)	1.5 (4.9)	2.0 (6.6)	m/min (feet/min)
	• Width	1550 (61)	1550 (61)	1550 (61)	1550 (61)	mm (inch)
	• Length for inner layer	4038 (159)	5088 (200)	5563 (219)	6548 (258)	mm (inch)
	• Length for outer layer	3930 (155)	5180 (204)	5630 (222)	6430 (253)	mm (inch)